| Sea               | t No.:   | Enrolment No   |          |
|-------------------|--|--|----------|
| Sul<br>Sul<br>Tir | oject<br>oject<br>ne:2:<br>ruction<br>1.<br>2. | GUJARAT TECHNOLOGICAL UNIVERSITY  SEMESTER- II(New course) • EXAMINATION (Remedial) – WINTER- 2015 Code: 3725201 Date: 08/12/201  Name: System Design 30 pm to 5:00 pm Total Marks: 7 ns: Attempt all questions. Make suitable assumptions wherever necessary. Figures to the right indicate full marks. | 15       |
| Q.1               | (a)<br>(b)                                     | Explain the concept of System Design in brief.  Describe in detail with examples about the embedded systems in  1. Home Environment  2. Office Environment   | 07<br>07 |
| Q.2               | (a)  | Explain in detail the following:  1. Single Layer PCB  2. Double Layer PCB  3. Multi Layer PCB   | 07       |
|                   | <b>(b)</b>                                     | Explain in about the decoupling at IC level and Board Level  OR  | 07       |
|                   | (b)  | Explain in detail about the Floating Point and Fixed Point Data formats.   | 07       |
| Q.3               | (a)<br>(b)                                     | Explain the Characteristic Impedance property of transmission lines on the hardware board for signal transmission. Explain in detail about the $I^2C$ Bus Interface and the generic software support for the $I^2C$ devices.   | 07<br>07 |
| Q.3               | (a)<br>(b)                                     | OR  Explain the following I/O data transfer techniques:  1. Program Driven I/O Transfer  2. Interrupt Driven I/O Transfer  3. Direct Memory Access I/O Transfer  Explain in detail about the basic components of any typical real time embedded  | 07<br>07 |
| Q.4               | (a)<br>(b)                                     | Explain the followings:  1. Compiler 2. Assembler 3. Linker 4. Debugger Explain the need for prototyping and prototyping using FPGA platforms.   | 07       |
|                   | (0)  | OR   | U/       |
| Q.4               | (a)<br>(b)                                     | Explain in brief Hardware-Software Co-Design Methodologies.  Explain in brief Chemical Etching: Principles and Mechanisms.   | 07<br>07 |

Explain in brief Environmental concerns in PCB industry.

(b) List down the high speed hardware system design challenges and explain any one.

Q.5

**07** 

**07** 

| Q.5 | (a)        | Explain in detail power consumption issues in Hardware-Software Co-Design. | 07 |
|-----|------------|--|----|
|     | <b>(b)</b> | Define a Real Time Embedded System and describe its characteristics.       | 07 |

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